



Politecnico
di Torino



Simulations and characterization of the first monolithic CMOS LGAD implemented in 110nm

2nd DRD3 week on Solid State Detectors R&D
CERN, 05/12/2024



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Motivation

Main driver: **ALICE 3 ToF layers**

Constraints:

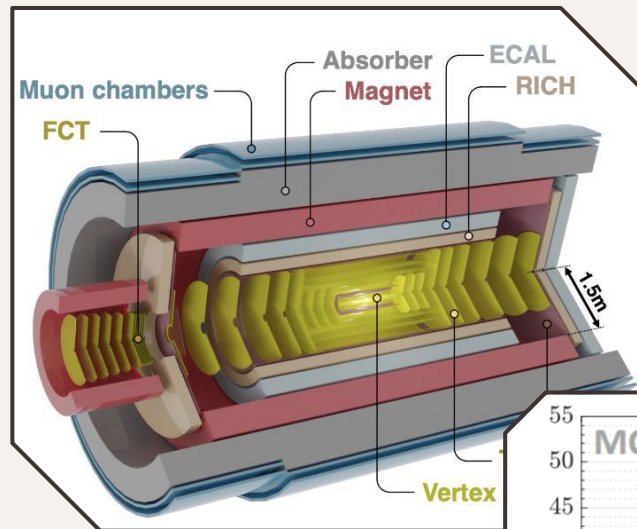
- Time resolution ≈ 20 ps
- Power consumption
- Material budget
- Cost

Monolithic timing detectors are considered as an option

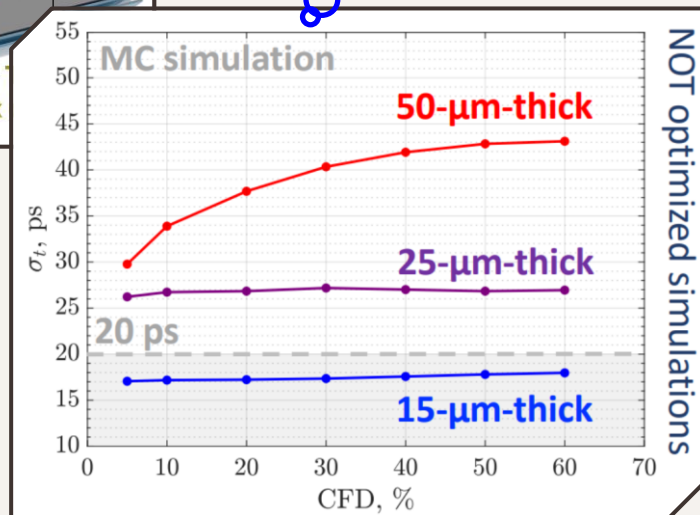
Other fields: 4D tracking, very low power pixel sensors (space), medical applications

Low Gain Avalanche Diodes (LGADs): workhorse for high resolution silicon timing detector.

From simulations: **<20ps** for thicknesses **<15 μ m**



CMOS LGAD:
a **MAPS** sensor
with internal gain



Starting point: ARCADIA monolithic sensors

Fully depleted MAPS in 110nm CMOS

Available **thicknesses**:

- 48um, 100um, 200um (full depletion demonstrate up to 400um)

Target **applications**:

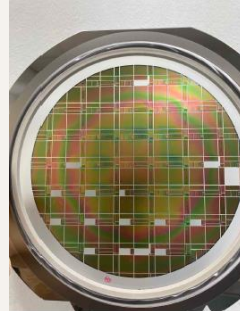
- Medical Imaging (PCT)
- Space applications
- HEP experiments
- X-ray imaging

3 engineering runs:

- 1st – mid 2021
- 2nd – beginning 2022
- 3rd – beginning 2023

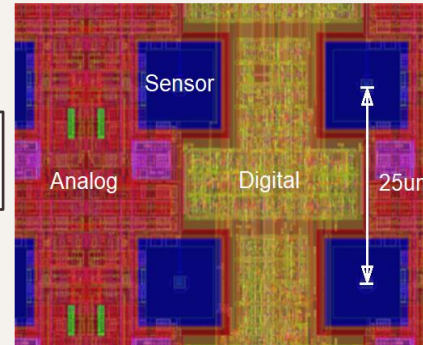
Main demonstrator (MD):

- Sensor array of **512x512 pixels**
- Pixel pitch: **25um**
- **Binary pixel** with **event-driven readout**

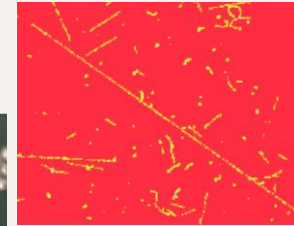


ARCADIA

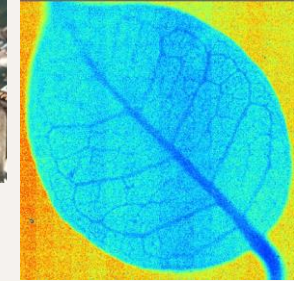
Andrea Patternò, Vertex 2021
ARCADIA Main Demonstrator



M. Rolo, **Pixel layout**

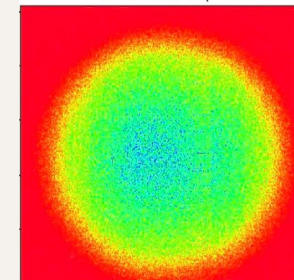


Cosmic Rays



X-ray image -
photon counting

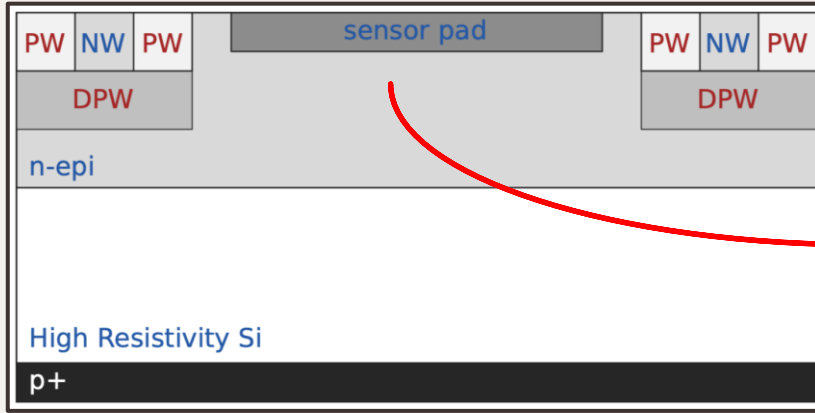
Incremental map



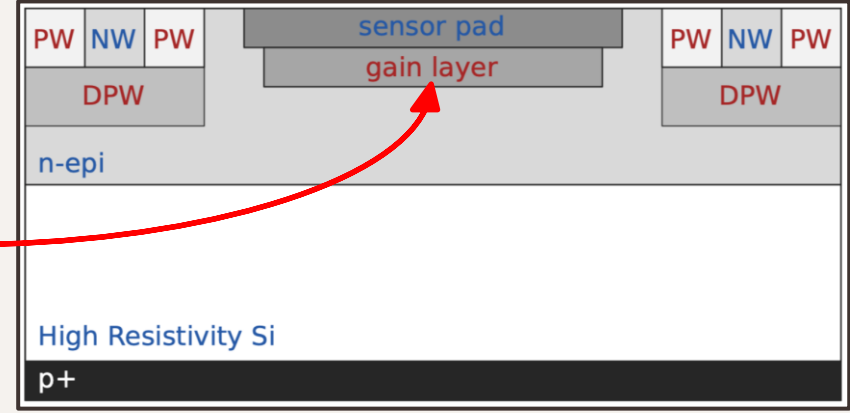
⁹⁰Sr source

ARCADIA MAPS: gain add-on option

ARCADIA pad sensor



ARCADIA pad sensor with gain



- Add-on **p-gain** below the collecting electrode starting from 3rd run
- Lfoundry CMOS 110nm with 48um active thickness
- ARCADIA production:
 - ↳ **passive structures** and **monolithic structures**
- Requires **negative bias** of the backside, **positive bias** at the sensor pad and **AC coupling** of readout electronics

MadPix

*Monolithic CMOS Avalanche Detector **PIX**elated Prototype*

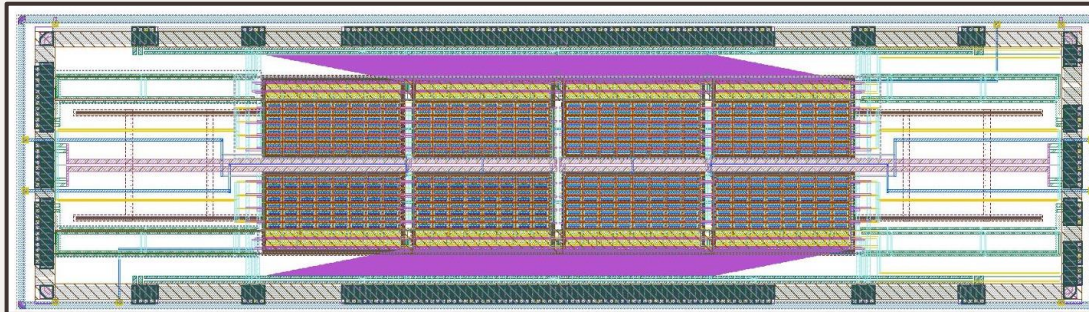
First prototype with **integrated electronics** and **gain layer**

Active thickness: 48 μm

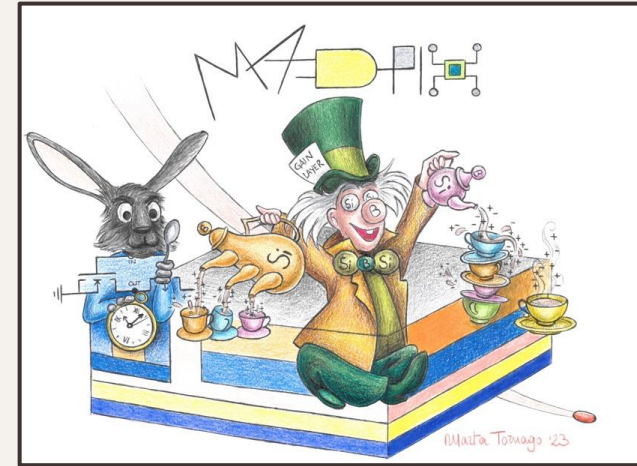
- **Backside HV**: allow full depletion \rightarrow -20 V to -40 V
- **Topside HV**: manage the gain \rightarrow 35 V to 65 V

» 8 matrices of 64 pixels each » 64 x 2 analogue outputs

» 4 flavours » Pixels of 250 μm x 100 μm



↑
Symmetrical
↓

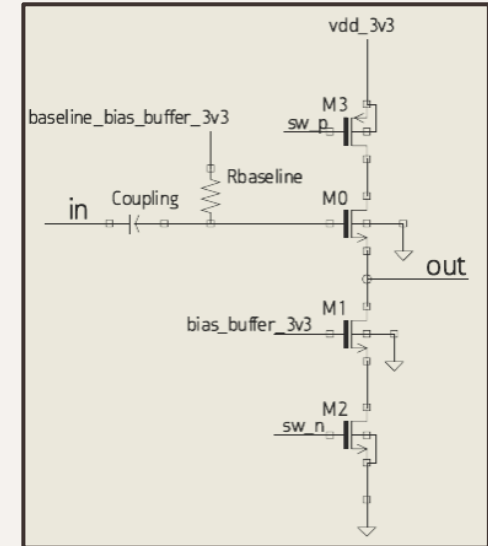
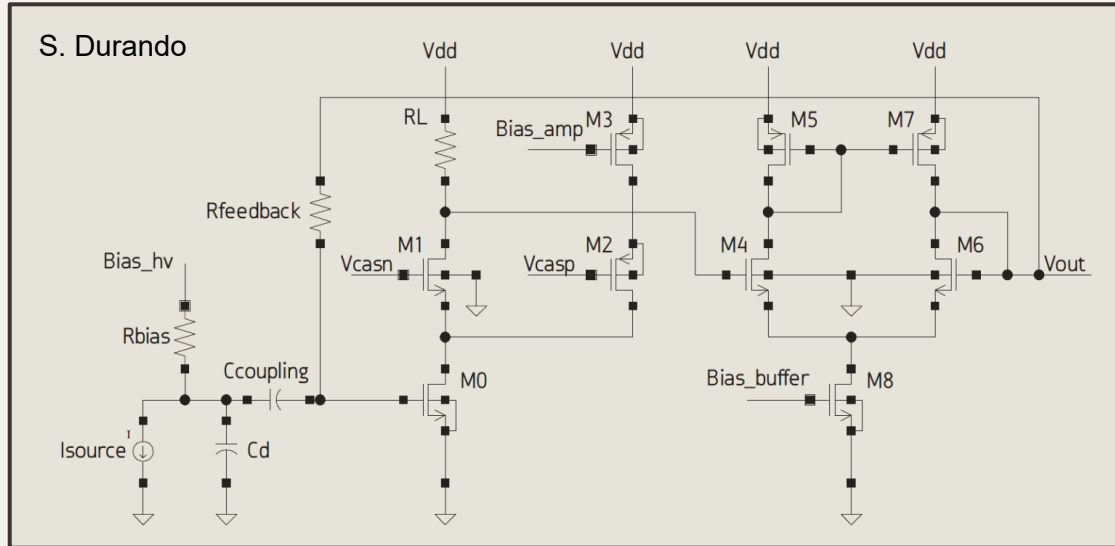


Thanks to M. Tornago

MadPix Electronics

- ❖ Cascoded common source + differential buffer (1.2V)
- ❖ FE **AC coupled** with sensor
- ❖ Power: **0.18mW/ch**

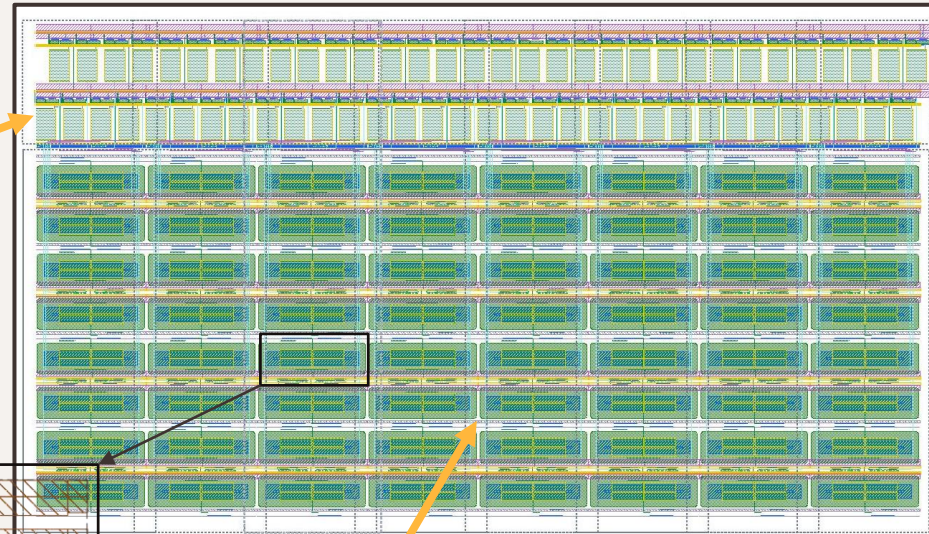
- ❖ Source follower (3.3V)
- ❖ AC coupled with FE
- ❖ Power: 1.65mW/ch



MadPix Layout

» 3.3V buffer out-pixel

» 1.2V **FE electronics in-pixel**



» 8x8 pixels in one matrix

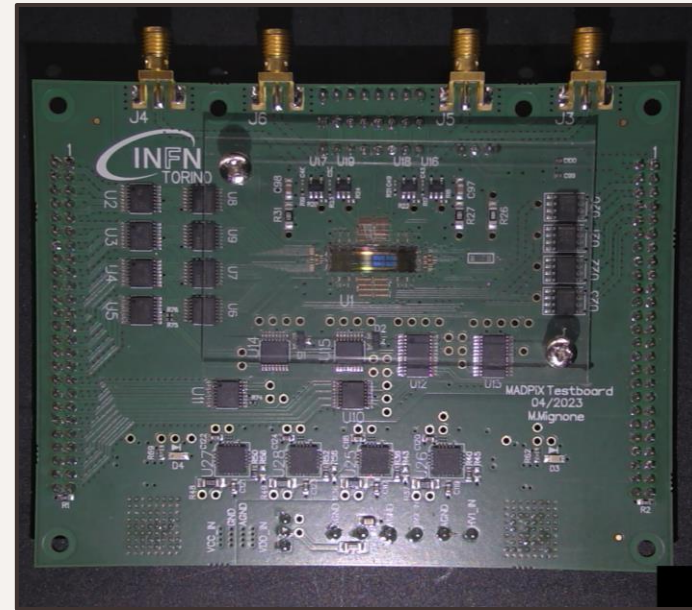
» Pixel dimension: non optimal for timing (Distortion term) but crucial in this R&D phase

↳ **Bigger pixels** can be implemented **in dedicated run**

MadPix Test Board

Controlled through FPGA (DACs, Digital potentiometers, Test pulse)

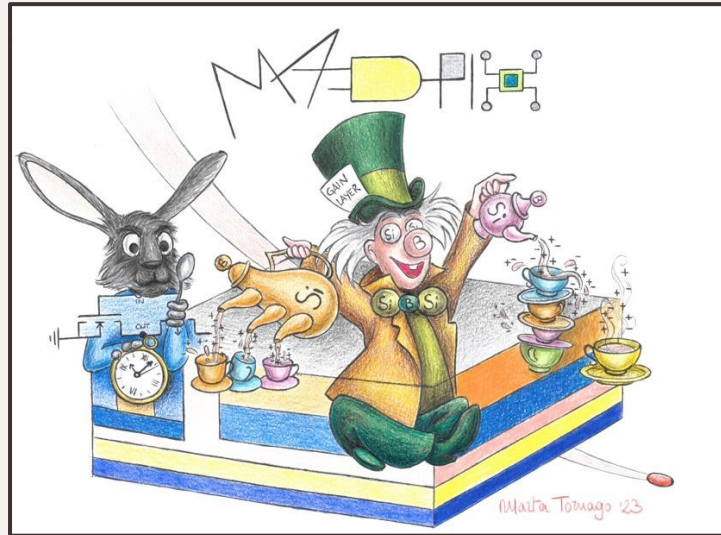
- 4 SMA driving 50 Ω line (top 4 matrices)
→ **Analogue** read-out (Oscilloscope/Digitizer)
- 4 **Discriminator** (bottom 4 matrices)
→ **Digital** read-out (FPGA)

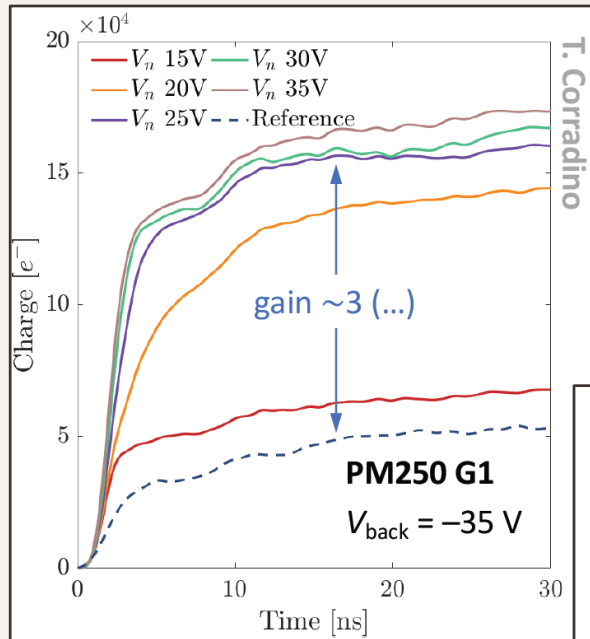


Only **four adjacent pixels** can be read simultaneously

- Board designed by Marco Mignone (INFN Torino)
- Firmware written by Richard Weadon (INFN Torino)

Chip Characterization

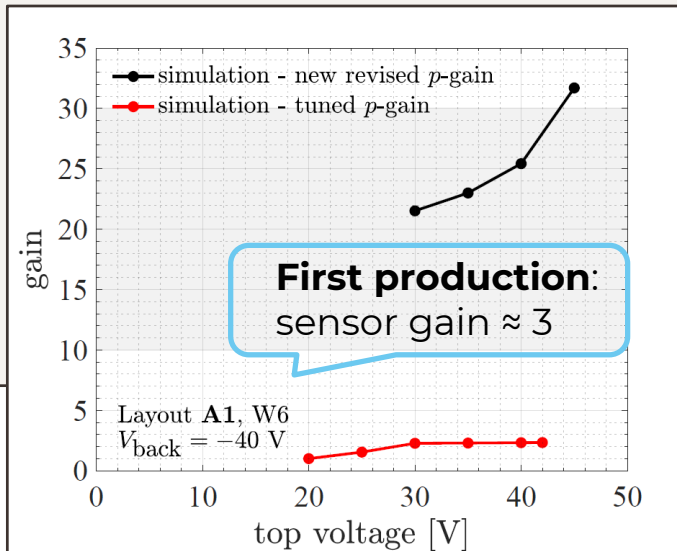
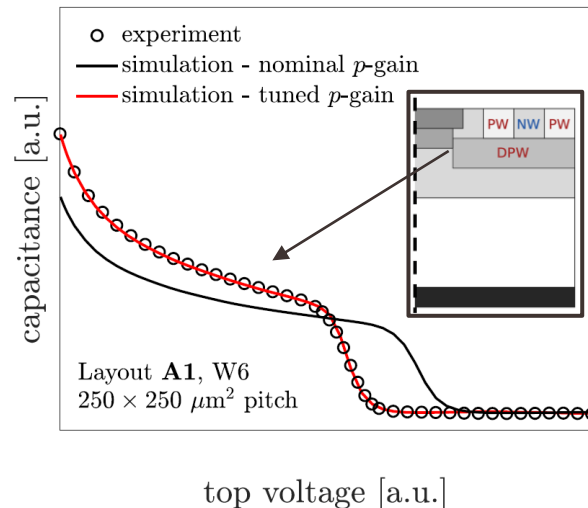




T. Corradino

First results

- Lateral **CV**
- P-gain **implantation energy is -2.5x** to recover mismatch (TCAD simulations)
- **Gain target** with nominal profile: **20-30**



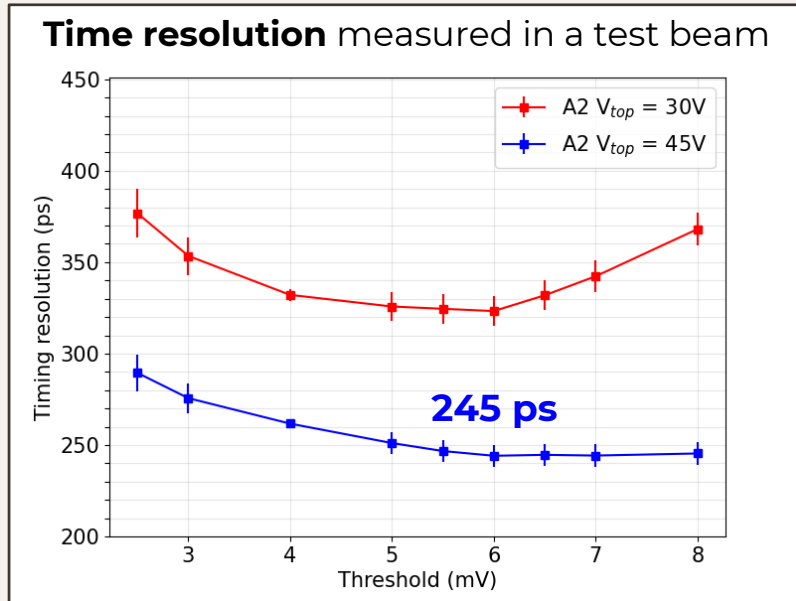
- **Passive structures** under focused **IR laser**
 - Backside Illumination
 - Integrated charge in time
- We have **gain**...
... but lower than expected

- Gain extraction using TCAD simulations with tuned p -gain profiles (TCAD simulations)
- **Gain simulated ≈ 3**
- **Good agreement** between data and simulation

<https://dx.doi.org/10.1088/1748-0221/19/07/P07033>

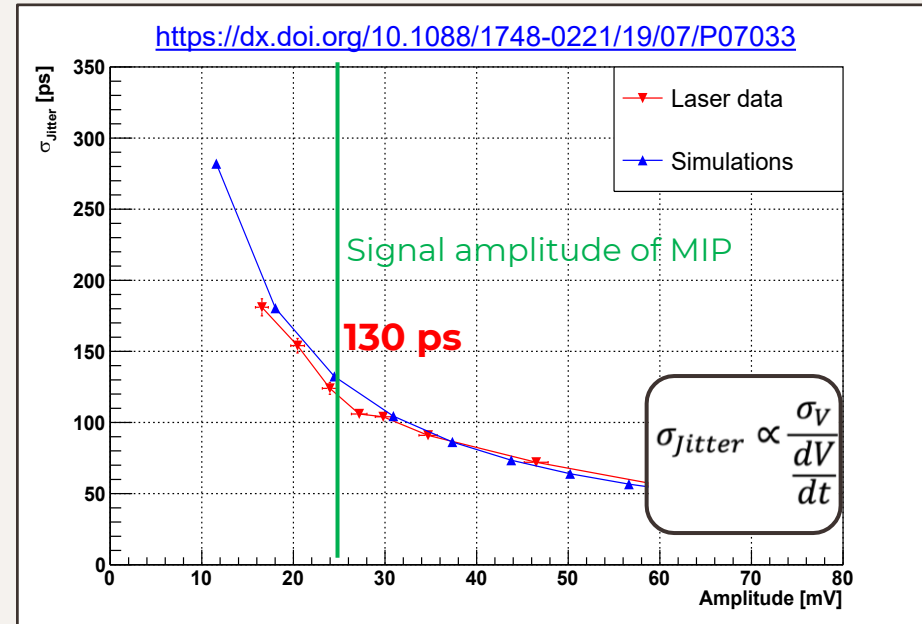
First test beam : Time resolution

October 2023



Jitter:

- RMS of the time difference between laser trigger out (TTL) and analogue output of MadPix (@ 50% signal amplitude)



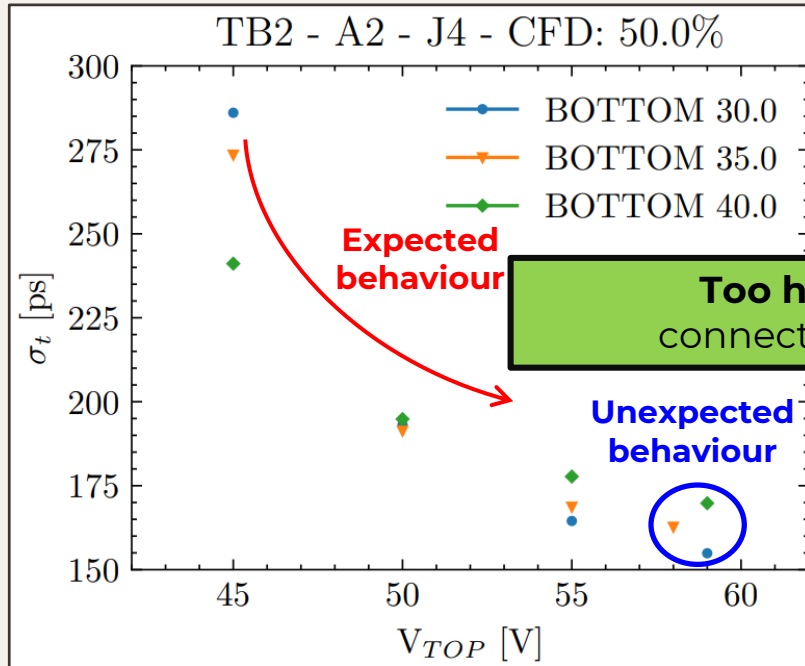
$$\sigma_t^2 = \sigma_{\text{Time Walk}}^2 + \sigma_{\text{Landau Noise}}^2 + \sigma_{\text{Distortion}}^2 + \sigma_{\text{Jitter}}^2 + \sigma_{\text{TDC}}^2$$

Time resolution of **245 ps** can **not** be explained with **jitter**

Main contributor: Sensor

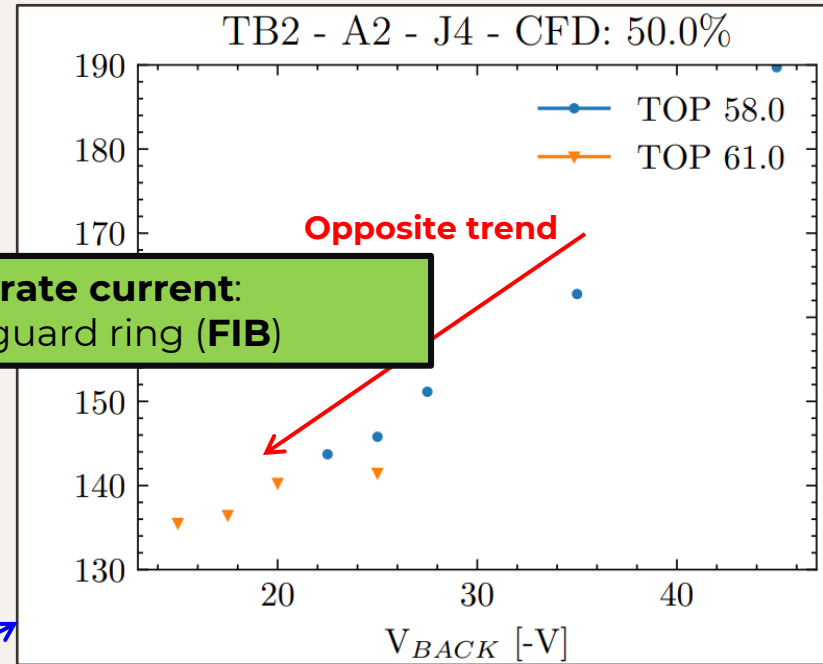
Second test beam: a lot to process

July 2024



Increasing the collection electrode voltage, the time resolution improves

Investigated

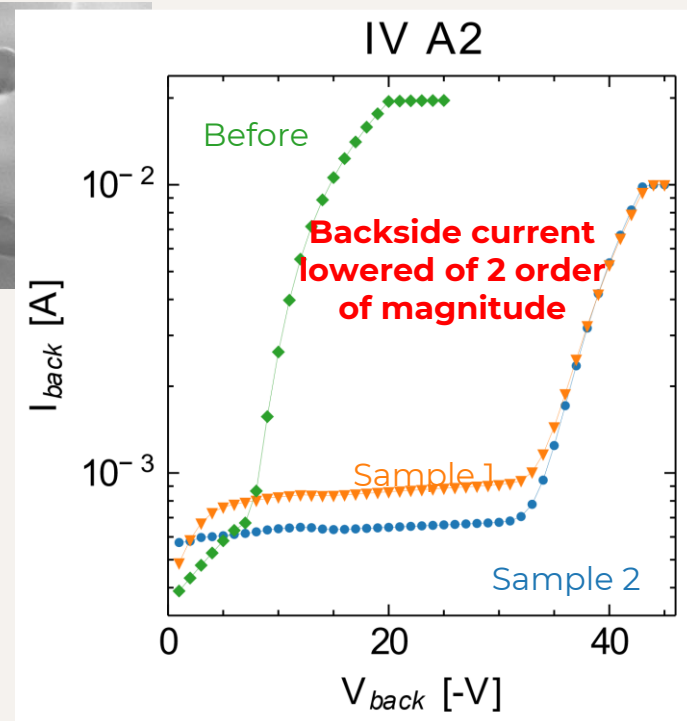
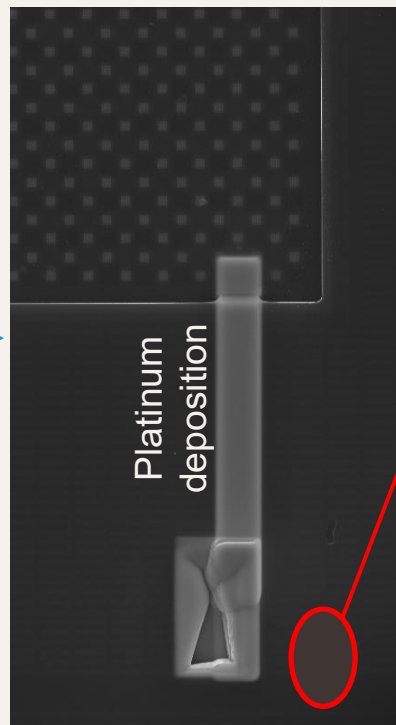


Decreasing the substrate voltage, the time resolution improves

**Too high substrate current:
connect floating guard ring (FIB)**

Solving the problem: Focused Ion Beam

Floating guard ring to be shorted



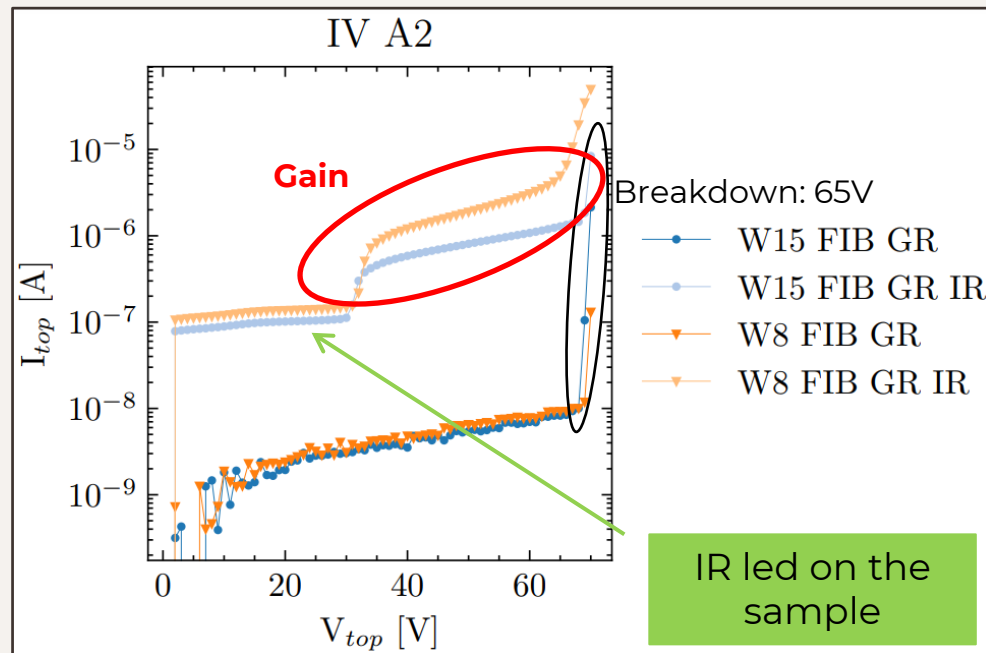
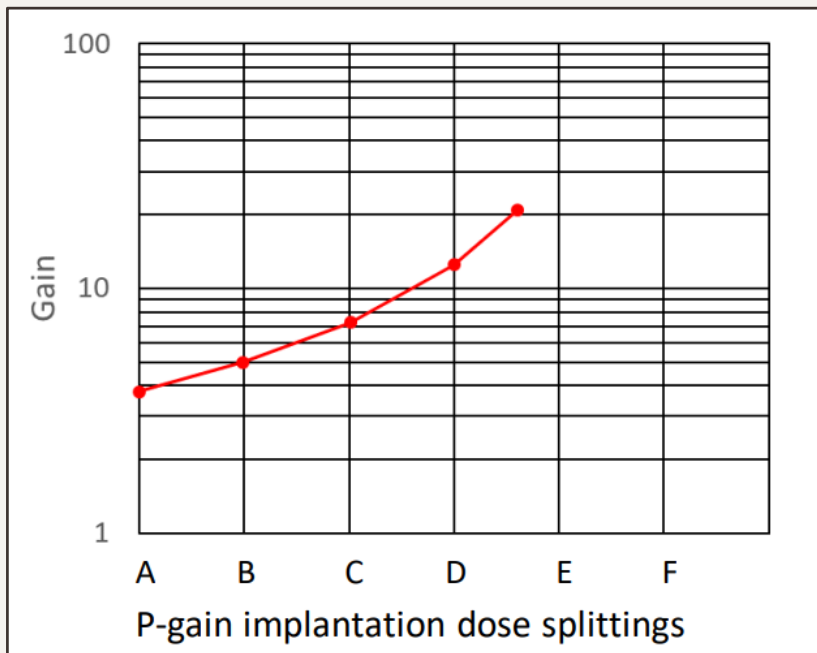
MadPix – Short loop

New production:
Increased gain

Short loop: same mask set with different implant dose -> optimization of sensor at low price

New **sensor** production with **higher gain** arrived in September 2024

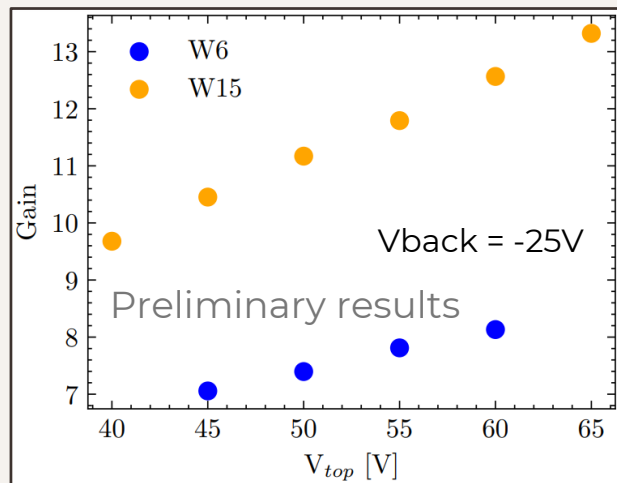
Expected **gain range: 5-20**



MadPix – Short loop

October 2024

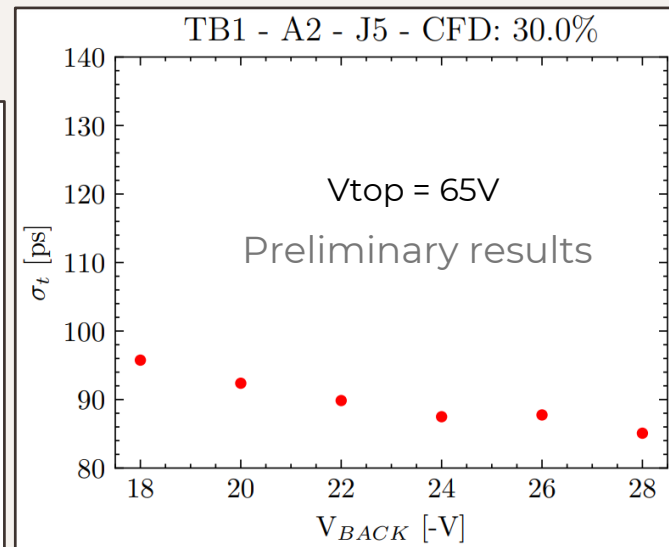
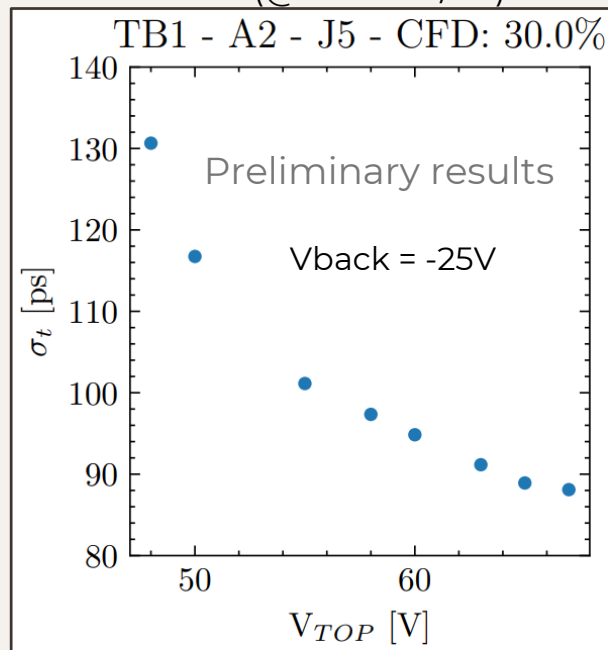
First estimation of **gain** using a non collimated radiation source of ^{55}Fe



$$\text{Gain} = \frac{\text{Peak [V/e]}}{\text{Electronics}_{\text{gain}} [\text{V/e}]}$$

From electronics simulations
matched with data

Time resolution sensor +
front end (@0.18mW/ch)

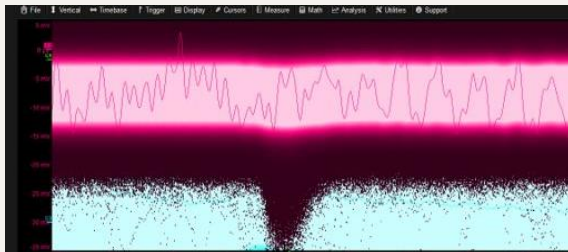


Time resolution sensor + front
end (@0.18mW/ch): 88 ps

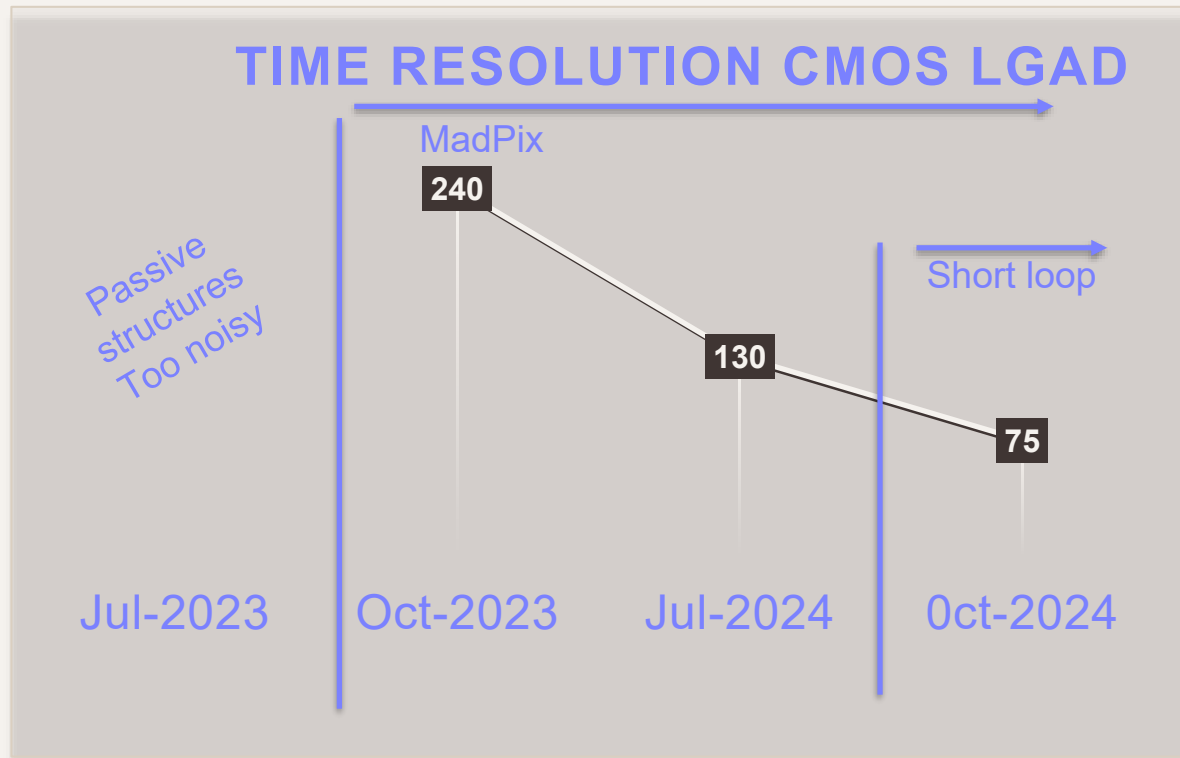
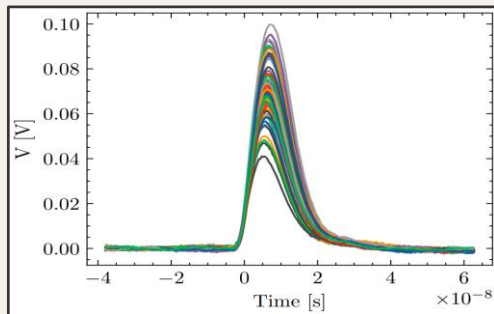
Time resolution sensor: ≈ 75 ps

Back where we started from

First signals observed in a test beam, passive structure with gain - 50um thick - July 2023



Signals observed in last test beam, MadPix with gain - 50um thick - Oct 2024



Conclusions and Outlook

- Prototype for timing application in 110nm technology design in the ARCADIA project
 - ↳ **MadPix**
- Test beam characterization of devices with **low gain ≈ 3**
 - ↳ Time resolution \approx **130ps** (Electronics + Sensor) but **high substrate current**
- Performed Focused Ion Beam (**FIB**) on multiple samples
 - ↳ Substrate **current: 2 orders of magnitude lower**
- Laboratory characterization of structure with **improved gain**
 - ↳ **Gain** of the sensor between **5 and 13**
- **Total time resolution** below **90ps** (@ 0.18mW/ch)
 - ↳ **Sensor** time resolution \approx **75ps**

What's next?

- Position – time correlation of MadPix test beam of March 2025 @ DESY
- Characterization of MadPix without gain
- Simulation activities to match test beam results
- Short loop with lower active thicknesses

Thank you for the attention!



Spare

Simulation matching

MonteCarlo simulation
of the sensor

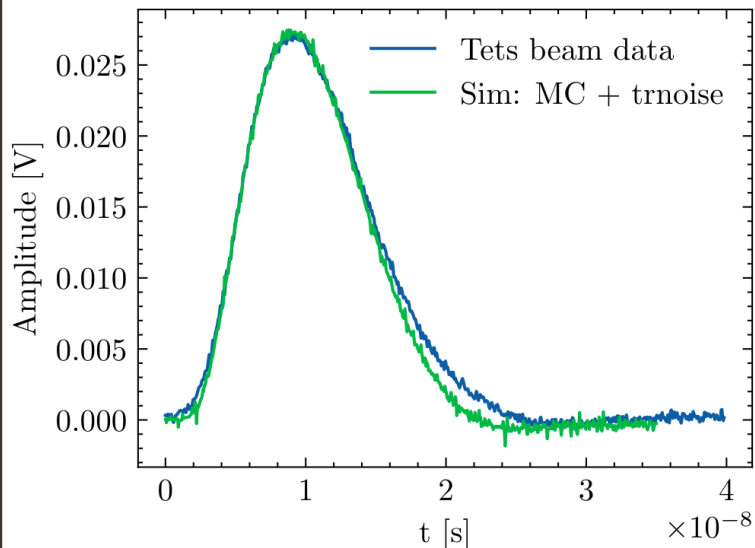


Transient noise
simulation of the
electronics



Comparison of
simulation results and
experimental data

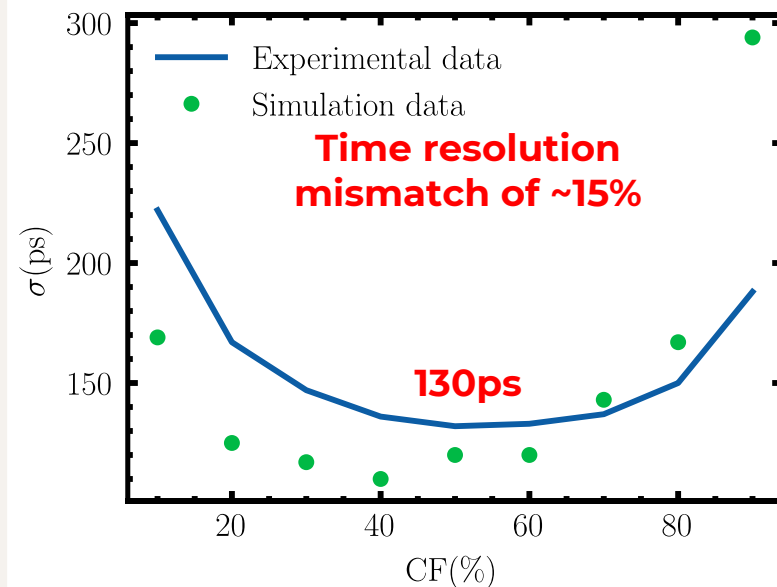
Channel 3 - Mean of 5 signals



Test beam data:
TOP -> 61V
BACK -> -15V

Simulation:
TOP -> 45V
BACK -> -40V

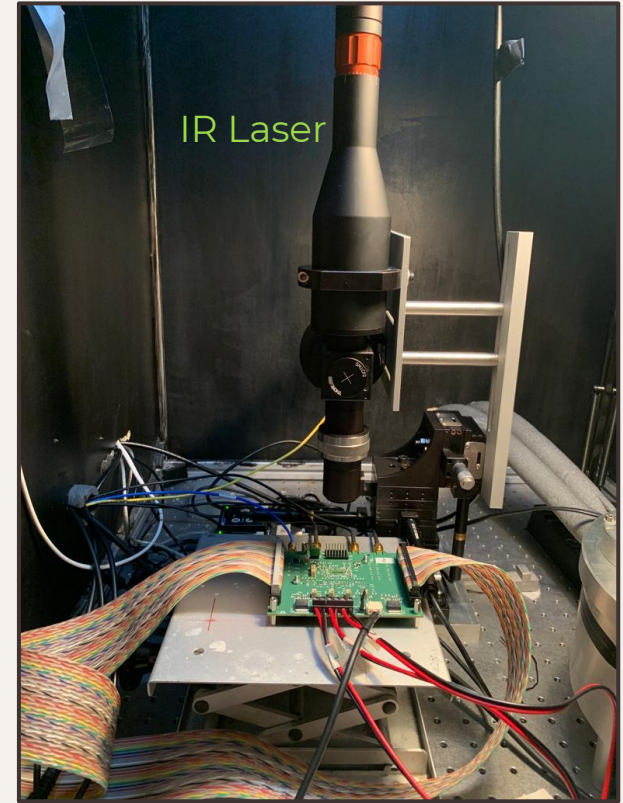
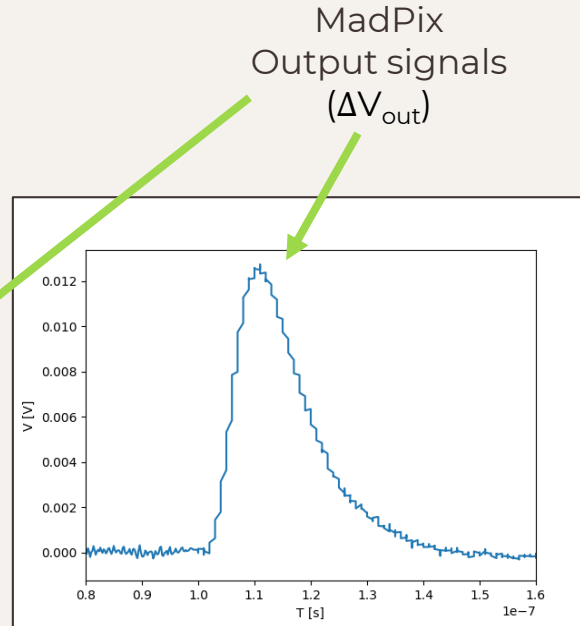
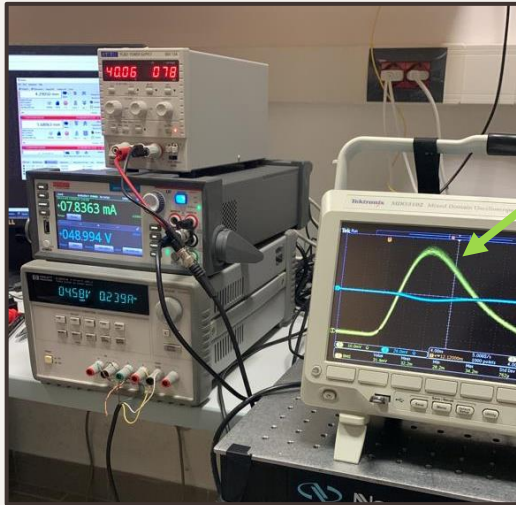
**Different biasing
condition!**
More tuning is
needed



Laser setup

📍 Optical characterization at UNITN (Trento)

- IR laser from the back of the sensor
- laser pulse ~ 100 ps
- laser spot ~ 20 μm



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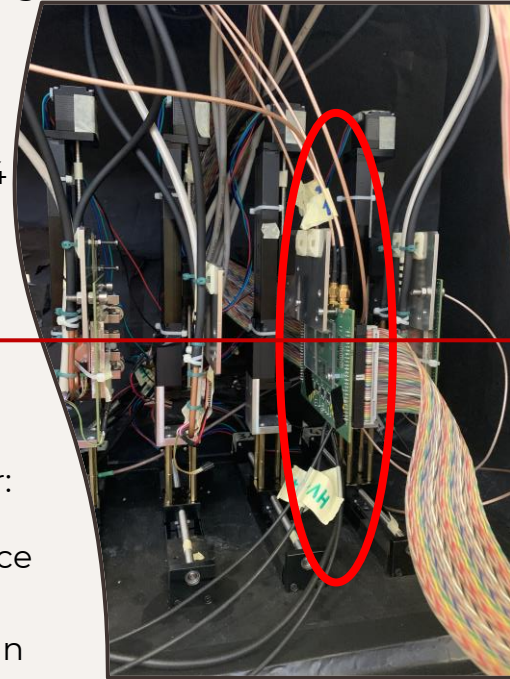
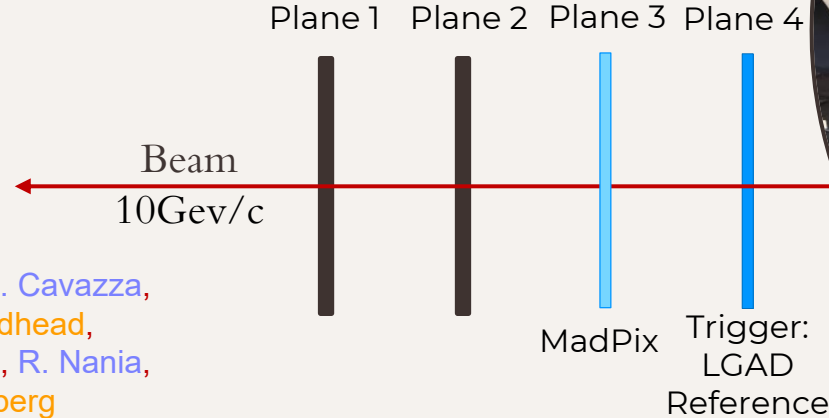
Madpix at the Test Beam

📍 Test beam setup in collaboration with INFN Bologna

In July 2024 **second test beam** with **MadPix**

→ at CERN Proton Synchrotron (PS)

→ with p/π of 10 GeV/c



M. Bregant, S. Bufalino, Z. Buthelezi, D. Cavazza,
M. Colocci, C. Ferrero, U. Follo, J. Goodhead,
S. Förtsch, G. Gioachin, M. Mandurrino, R. Nania,
B. Sabiu, G. Souza, S. Strazzi, S. Wimberg

INFN Torino,
INFN Bologna,
iThemba LABS,
Universidade de São Paulo

- » 4 planes telescope
- » MadPix linked to a Xilinx FPGA controlled in control room
- » Readout → Oscilloscope for signal acquisition

Passive structures characterization

I(V) scan to study the sensor behavior

New production:
Increased gain

I_{back} → current between **p⁺** on the backside and the **p-wells**
→ Punch through for $V_{back} > 45V$

DC Gain → ratio between leakage current of gain and no gain structures measured in n⁺ **collection electrode** illuminating with IR LED

